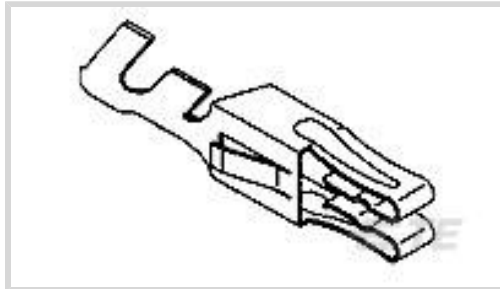




Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Contacts



Contact Type: **Socket**

Connector System: **Wire-to-Board**

Wire Size: 1.25 – 2 mm²

Features

Product Type Features

Connector System	Wire-to-Board
Sealable	No
Connector & Contact Terminates To	Wire & Cable

Contact Features

Contact Retention Within Housing	With 150 μin
Wire Contact Termination Area Plating Material Finish	Bright
Wire Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material Finish	Bright
Contact Base Material	Copper Alloy
Contact Type	Socket
Contact Mating Area Plating Material	Tin-Lead

Termination Features

Termination Method to Wire & Cable	Crimp
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Mechanical Attachment

Contact Retention Type Within Housing	Locking Lance
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Dimensions

Accepts Wire Insulation Diameter Range	2.29 – 3.68 mm [.09 – .145 in]
Wire Size	1.25 – 2 mm ²



Operation/Application

Circuit Application

Power & Signal

Packaging Features

Packaging Quantity

1500

Packaging Method

Strip

Product Compliance

For compliance documentation, visit the product page on [TE.com](https://www.te.com)>

EU RoHS Directive 2011/65/EU

Not Compliant

EU ELV Directive 2000/53/EC

Not Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUNE 2022 (224)
 Candidate List Declared Against: JAN 2022 (223)
 SVHC > Threshold:
 Pb (13% in Component Part)

Article Safe Usage Statements:

Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

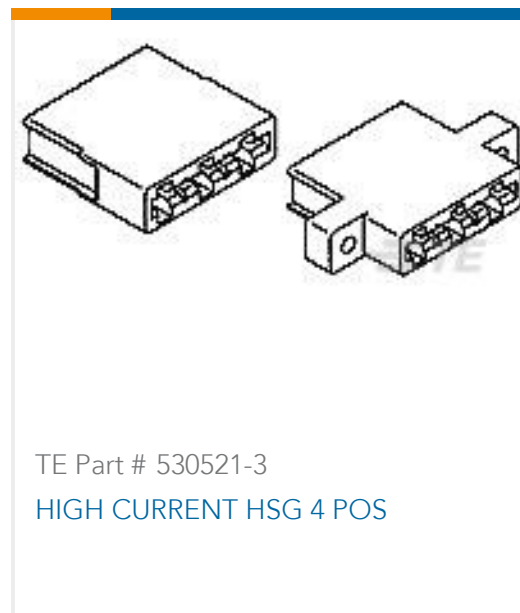
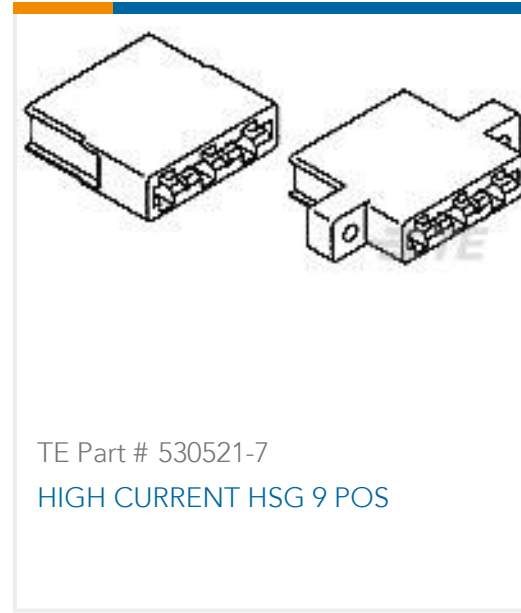
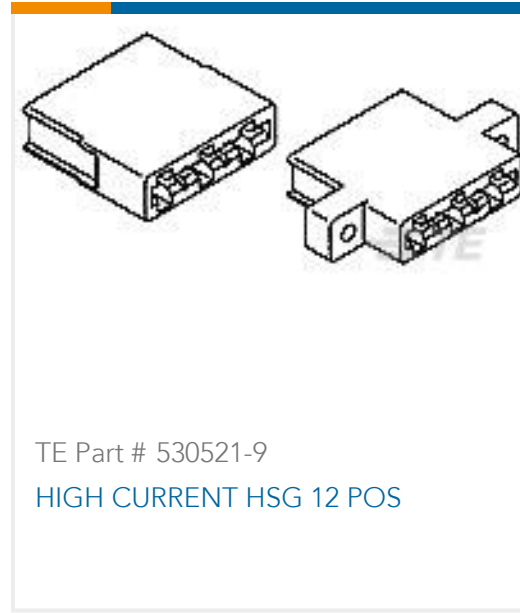
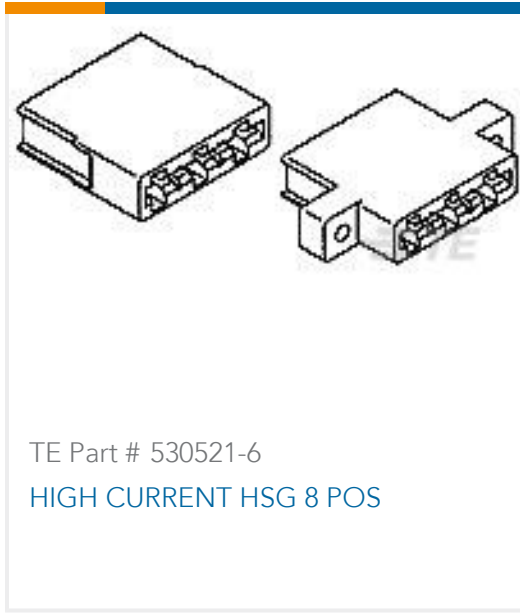
Solder Process Capability

Not applicable for solder process capability

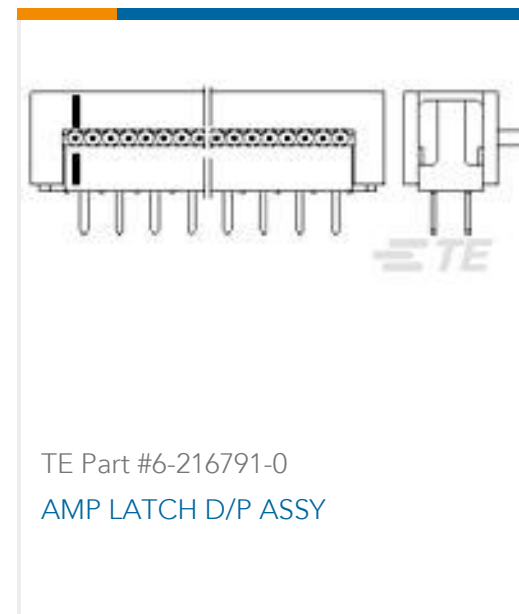
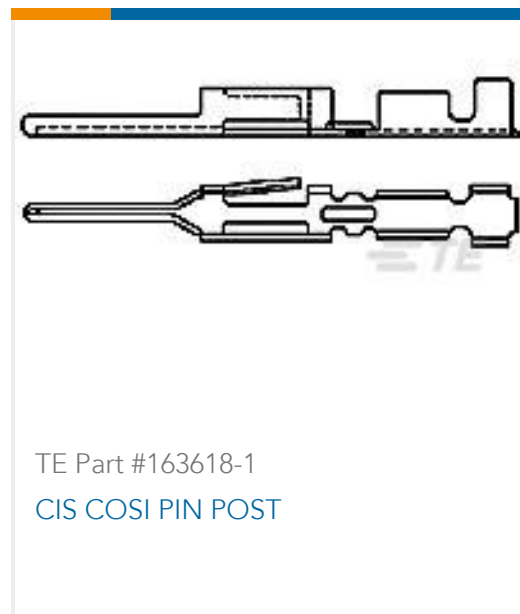
Product Compliance Disclaimer

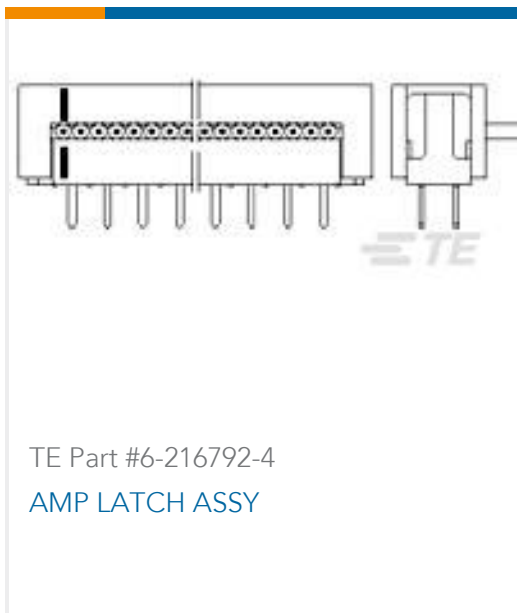
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought





Documents

Product Drawings

HIGH CURRENT CONT. STRIP

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_530517-2_U.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_530517-2_U.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_530517-2_U.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English